

Bill of materials for SoftRock v6 Exciter PA board, 40m

Design by: Jan (G0BBL), Alan (M0PUB) and John (G8BTR)

BOM prepared by: Tony, KB9YIG, 9/19/06

	used where	quantity	
Resistors			
2.21k, 1/4W, 1%	R1	1	
475, 1/4W, 1%	R2, R6	2	
22.1, 1/4W, 1%	R3	1	
68.1, 1/4W, 1%	R4	1	
15, 1/4, 1%	R5	1	
2k pot	R7	1	
1.0, 1/4W, 5%	R8	1	
Capacitors	used where	quantity	
820pF ceramic, 5%	C1, C4, C14	3	
330pF ceramic, 5%	C2	1	
0.1uF, ceramic, 10%	C3, C7, C12	3	
0.1uF, smt 1206	C5, C8, C10, C11, C24	5	one spare provided in kit
0.01uF ceramic, 5%	C6	1	
10uF/16 VDC Electrolytic	C9, C16, C17, C18, C19, C20, C21, C22, C23	9	
470pF ceramic, 5%	C13, C15	2	
Inductors / transformers	used where	quantity	
3.3uH, T25-2 core (red), 31T, #30 wire	L1	1	
1.4uH, T25-2 core (red), 20T, #30 wire	L2	1	
35uH, 10T, #26 on FT3743 core (gray)	L3	1	
1.1uH, T30-2 core (red), 16T of #26	L4, L5	2	
each bifilar primary winding 9T, #30 wire	T1	1	
18T secondary on T30-2 core, #30 wire	T1		
4T each, #30 wire on BN-43-2402 core	T2	1	
10uH molded inductor	RFC1	1	
4T, #26 wire on BN-43-2402 core	RFC2	1	
Wire, AWG #26		8 feet	
Wire, AWG #30		8 feet	
Transistors	used where	quantity	
2N2222, TO18	Q1	1	
2N3866, TO39	Q2	1	
Diodes	used where	quantity	
1N4003	D1	1	
Connectors	used where	quantity	
three-pin header sockets, 0.1 inch centers	P1, P3	2	
five-pin header sockets, 0.1 inch centers	P2	1	
Circuit boards	used where	quantity	
SR_v6_pa	PA circuit board	1	
Hardware	used where	quantity	
Clip-on TO-18 heatsink	on Q1 prior to soldering transistor to board	1	
Clip-on TO-39 heatsink	on Q2 prior to soldering transistor to board	1	

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